



## **SCHOTTKY BARRIER DIODES**

**SD103AWS ~ 103CWS** 



SOD-323GW

SOD-323GW Surface Mount Plastic Package RoHS compliant

**Device Marking** 

SD103AWS: S4 SD103BWS: S5 SD103CWS: S6

#### **FEATURES:**

- 1. High Current Capability
- 2. Low Forward Voltage Drop

## APPLICATION:

The fast switching make it ideal for protection of MOS devices, steering, biasing, and coupling diodes for fast switching and low logic level applications and for general purpose applications.

## **ABSOLUTE MAXIMUM RATINGS** (Ta = 25 °C Unless otherwise specified)

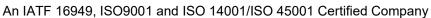
PARAMETER	CVMDOL	VALUE			
FARAMETER	SYMBOL	SD103AWS SD103BWS SD103	SD103CWS	UNIT	
Repetitive Peak Reverse Voltage	$V_{RRM}$	40	30	20	V
Working Peak Reverse Voltage	$V_{RWM}$	40	30	20	V
DC Blocking Voltage	$V_R$	40	30	20	V
RMS Reverse Voltage	V <sub>R (RMS)</sub>	28	21	14	V
Maximum average forward rectified current	I <sub>FM</sub> <sup>1</sup>		350		mA
Peak forward surge current 8.3 ms single half sinewave	I <sub>FSM</sub>	1.5		Α	
Power Dissipation Ta=25°C	$P_D^{-1}$	200		mW	
Operating and Storage Temperature Range	$T_{j},T_{stg}$	-50 to +150		°C	

## THERMAL RESISTANCE

Junction to Ambient in free air	R <sub>th (i.a)</sub> 1	500	°C/W
oundadir to 7 timble it in noo un	<b>' `</b> th (j-a)	300	0, 11



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**ELECTRICAL CHARACTERISTICS at** (Ta = 25 °C Unless otherwise specified)

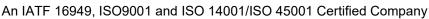
PARAMETER		SYMBOL	TEST CONDITION	VALUE			UNIT	
PARAMETE	PARAIVIETER		STMBOL TEST CONDITION		TYP	MAX	UNII	
Davis na a Dua akalawa	SD103AWS			40			V	
Reverse Breakdown Voltage	SD103BWS	$V_{(BR)R}^{2}$	I <sub>R</sub> =100μΑ	30			V	
Vollage	SD103CWS			20			V	
Forward Voltage		V	I <sub>F</sub> =20mA			0.37	V	
Forward Voltage		$V_{F}$	I <sub>F</sub> =200mA			0.60	V	
	SD103AWS		V <sub>R</sub> =30V			5.0	μA	
Reverse Current	SD103BWS	I <sub>R</sub> <sup>2</sup>	$I_R^2$	V <sub>R</sub> =20V			5.0	μΑ
	SD103CWS		V <sub>R</sub> =10V			5.0	μΑ	
DYNAMIC CHARACTERISTICS								
Total Capacitance Type ju capacitance	nction	Ст	V <sub>R</sub> =0V, f=1MHz		50		pF	
Reverse Recovery Time		t <sub>rr</sub>	$I_F = I_R = 200 \text{mA}, I_{rr} = 0.1 \text{ x } I_R,$ $R_L = 100 \Omega$	1	10		ns	

## Notes:

- 1. Mounted on FR-4 board with recommended pad layout
- 2. Short duration test pulse used to minimize self heating effect



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## TYPICAL CHARACTERISTICS CURVES

Fig 1: Forward Characteristics

100

T=100°C

T=25°C

100

T=25°C

FORWARD VOLTAGE V<sub>F</sub> (mV)

Fig 3: Reverse Characteristics

Fig 3: Reverse Characteristics

T<sub>s</sub>=100°C

T<sub>s</sub>=100°C

T<sub>s</sub>=25°C

REVERSE Voltage V<sub>s</sub> (V)

Fig 2: Capacitance Characteristics

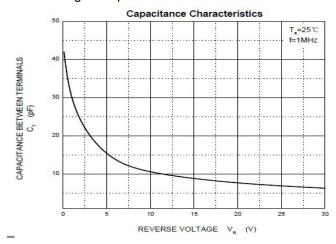


Fig 4: Power Derating Curve

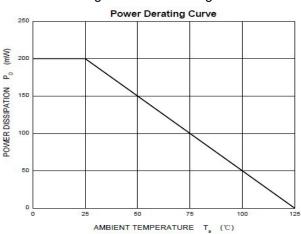
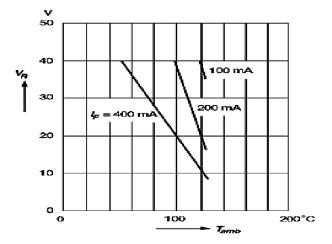


Fig 5: Blocking Voltage Duration Versus Temperature at Various Average Forward Currents



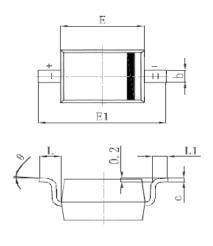


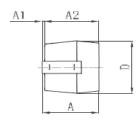




## **PACKAGE DETAILS**

SOD-323GW Plastic Package





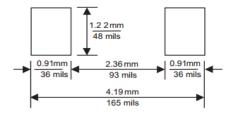
Min.(mm)		Max.(mm)	
		1	
(	)	0.1	
0.	.8	0.9	
0.2	25	0.35	
0.08		0.15	
1.	2	1.4	
1.6		1.8	
2.5		2.7	
0.475 REF			
0.25		0.4	
0°		8°	
	0.2 0.2 0.08 1. 1. 2.	0 0.8 0.25 0.08 1.2 1.6 2.5 0.479	

All dimensions are in mm

## **Mechanical Data**

- 1. SOD-323GW Small Outline Plastic Package
- 2. Polarity: Color band denotes cathode end
- 3. Epoxy UL: 94V-0
- 4. Mounting Position: Any

# **Recommended Pad Layout**







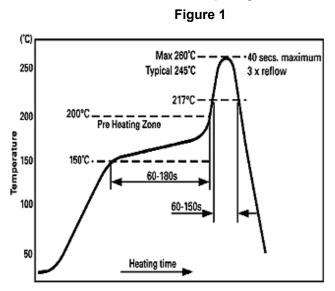


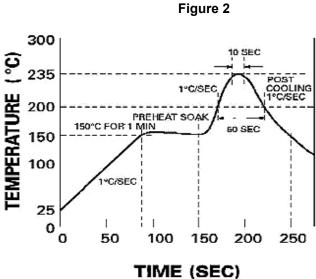
#### **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





## Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat		
– Temperature Range	150-170°C	150-200°C
– Time	60-180 seconds	60-180 seconds
Time maintained above:		
– Temperature	200°C	217°C
– Time	30-50 seconds	60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max.



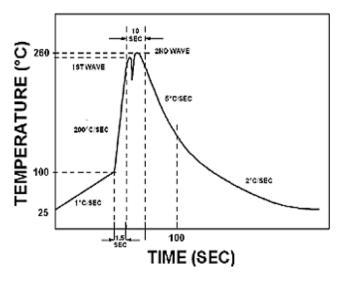


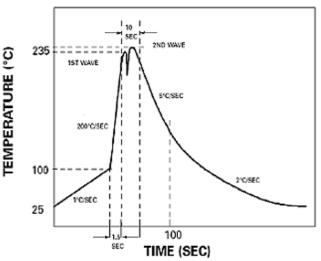


#### **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





#### **Wave Profiles in Tabular Form**

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Vithin 125°C of Solder Tem
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max







# Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

#### **Shelf Life of CDIL Products**

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

#### Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level			
Level	Time	Condition	
1	Unlimited	≤30 °C / 85% RH	
2	1 Year	≤30 °C / 60% RH	
2a	4 Weeks	≤30 °C / 60% RH	
3	168 Hours	≤30 °C / 60% RH	
4	72 Hours	≤30 °C / 60% RH	
5	48 Hours	≤30 °C / 60% RH	
5a	24 Hours	≤30 °C / 60% RH	
6	Time on Label(TOL)	≤30 °C / 60% RH	







#### **Customer Notes**

#### **Component Disposal Instructions**

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

## **Disclaimer**

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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